

IN THE

UNITED STATES PATENT AND TRADEMARK OFFICE

inventor(s):

Hyung-Jik BYUN, et al.

Serial No.:

10/053,278

Examiner:

Not yet assigned

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Group Art Unit:

1725

Title:

SEMICONDUCTOR CHIP PACKAGE COMPRISING ENCHANCED PADS

Box DD

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INFORMATION DISCLOSURE STATEMENT

Sir:

This Information Disclosure Statement is submitted:

under 37 CFR 1.97 (b), or

(Within three months of filing national application; or date of entry of International application; or before mailing date of first office action on the merits; whichever occurs last)

Applicant(s) submit herewith Form PTO 1449- Information Disclosure Citation together with copies of patents, publications or other information of which applicant(s) are aware, which applicant(s) believe(s) may be material to the examination of this application and for which there may be a duty to disclose in accordance with 37 CFR 1.56.

It is requested that the information disclosed herein be made of record in this application.

Any deficiency or overpayment should be charged or credited to deposit account number 13-1703. A duplicate copy of this sheet is enclosed.



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PATENT TRADEMARK OFFICE

Respectfully submitted,

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ON 8-27-03